



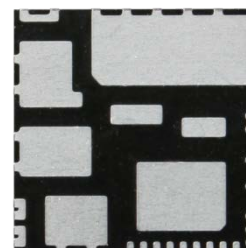
Integrated Power Module for Small Appliance Motor Drive Applications

Description

IRSM836-025MA is a 2A, 500V Integrated Power Module (IPM) designed for advanced appliance motor drive applications such as energy efficient fans and pumps. IR's technology offers an extremely compact, high performance AC motor-driver in an isolated package. This advanced IPM offers a combination of IR's low $R_{DS(on)}$ Trench MOSFET technology and the industry benchmark 3-phase high voltage, rugged driver in a small PQFN package. At only 12x12mm and featuring integrated bootstrap functionality, the compact footprint of this surface-mount package makes it suitable for applications that are space-constrained. Integrated over-current protection, fault reporting and under-voltage lockout functions deliver a high level of protection and fail-safe operation. IRSM836-025MA functions without a heat sink.

Features

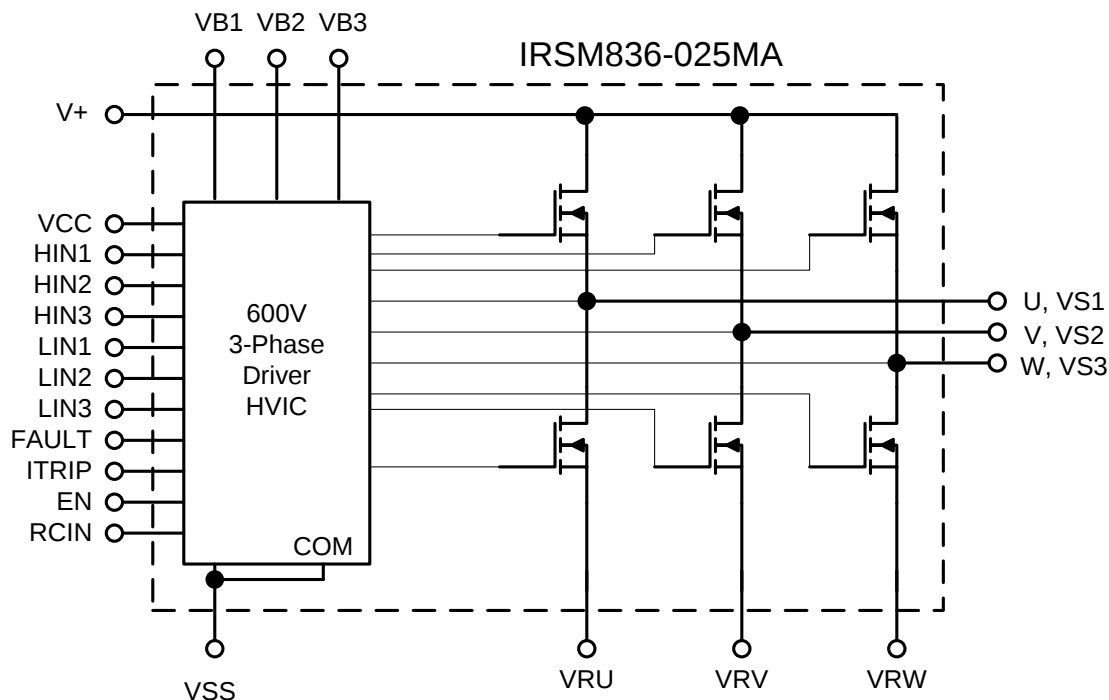
- Integrated gate drivers and bootstrap functionality
- Open-source for leg-shunt current sensing
- Protection shutdown pin
- Low $R_{DS(on)}$ Trench FREDFET
- Under-voltage lockout for all channels
- Matched propagation delay for all channels
- Optimized dV/dt for loss and EMI trade offs
- 3.3V Schmitt-triggered active high input logic
- Cross-conduction prevention logic
- Motor power range up to ~90W, without heat sink
- Isolation 1500VRMS min



Base Part Number	Package Type	Standard Pack		Orderable Part Number
		Form	Quantity	
IRSM836-025MA	36L PQFN 12 x 12 mm	Tape and Reel	2000	IRSM836-025MATR
		Tray	800	IRSM836-025MA

All part numbers are PbF

Internal Electrical Schematic



Absolute Maximum Ratings

Absolute maximum ratings indicate sustained limits beyond which damage to the module may occur. These are not tested at manufacturing. All voltage parameters are absolute voltages referenced to VSS unless otherwise stated in the table.

Symbol	Description	Min	Max	Unit
BV_{DSS}	MOSFET Blocking Voltage	---	500	V
$I_O @ T=25^{\circ}C$	DC Output Current per MOSFET	---	2	A
I_{OP}	Pulsed Output Current (Note 1)	---	11	
$P_d @ T_C=25^{\circ}C$	Maximum Power Dissipation per MOSFET	---	25	W
V_{ISO}	Isolation Voltage (1min) (Note 2)	---	1500	V_{RMS}
T_J	Operating Junction Temperature	-40	150	$^{\circ}C$
T_L	Lead Temperature (Soldering, 30 seconds)	---	260	$^{\circ}C$
T_S	Storage Temperature	-40	150	$^{\circ}C$
$V_{S1,2,3}$	High Side Floating Supply Offset Voltage	$V_{B1,2,3} - 20$	$V_{B1,2,3} + 0.3$	V
$V_{B1,2,3}$	High Side Floating Supply Voltage	-0.3	500	V
V_{CC}	Low Side and Logic Supply voltage	-0.3	20	V
V_{IN}	Input Voltage of LIN, HIN, I_{TRIP} , EN, RCIN, FLT	$V_{SS} - 0.3$	$V_{CC} + 0.3$	V

Note 1: Pulse Width = 100 μ s, $T_C = 25^{\circ}C$, Duty=1%.

Note 2: Characterized, not tested at manufacturing

Qualification Information†

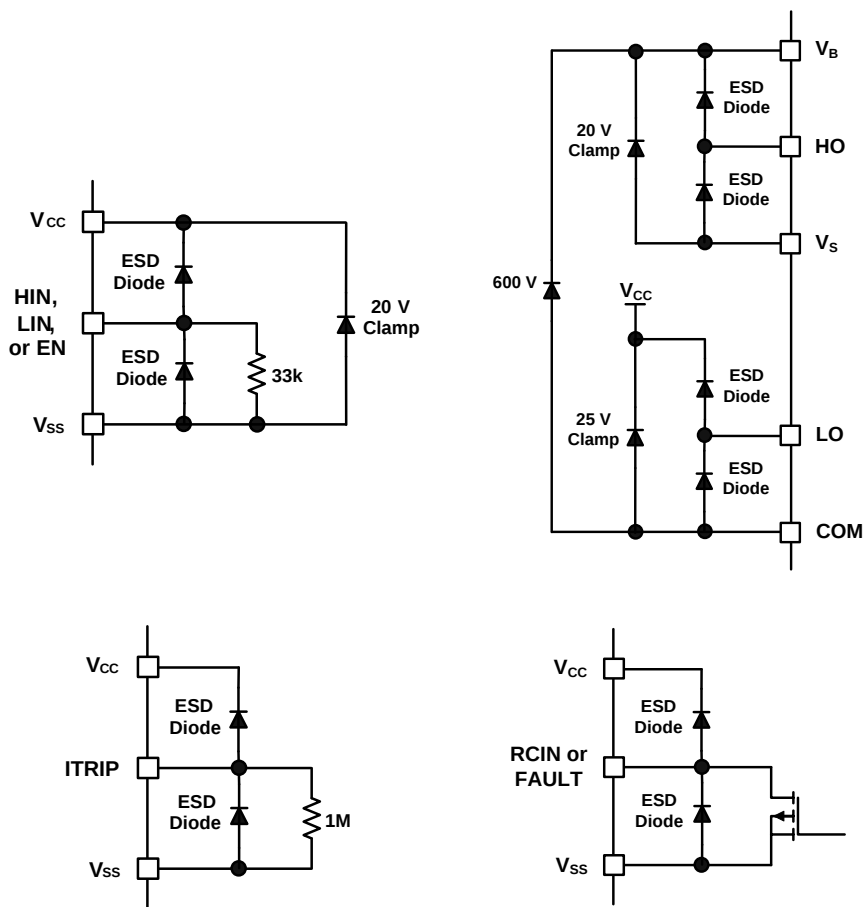
Qualification Level		Industrial ^{††} (per JEDEC JESD 47E)
Moisture Sensitivity Level		MSL3 ^{†††} (per IPC/JEDEC J-STD-020C)
ESD	Machine Model	Class B (per JEDEC standard JESD22-A115)
	Human Body Model	Class 2 (per standard ESDA/JEDEC JS-001-2012)
RoHS Compliant		Yes

† Qualification standards can be found at International Rectifier's web site <http://www.irf.com/>

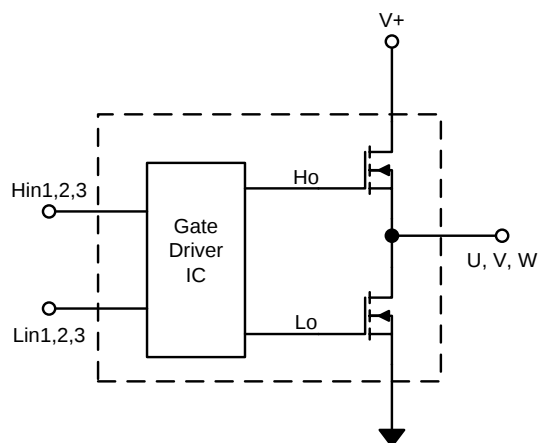
†† Higher qualification ratings may be available should the user have such requirements. Please contact your International Rectifier sales representative for further information.

††† Higher MSL ratings may be available for the specific package types listed here. Please contact your International Rectifier sales representative for further information.

Input/Output Pin Equivalent Circuit Diagrams



Input-Output Logic Level Table



EN	Itrip	Hin1,2,3	Lin1,2,3	U,V,W
1	0	1	0	V+
1	0	0	1	0
1	0	0	0	off
1	1	X	X	off
0	X	X	X	off

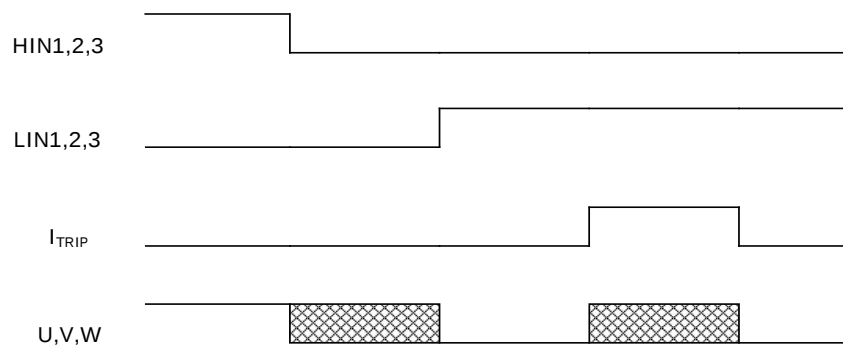


Figure 1: Input/Output Logic Diagram

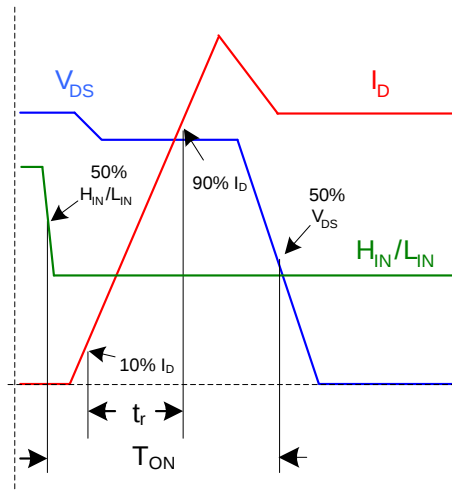


Figure 2a: Input to Output propagation turn-on delay time.

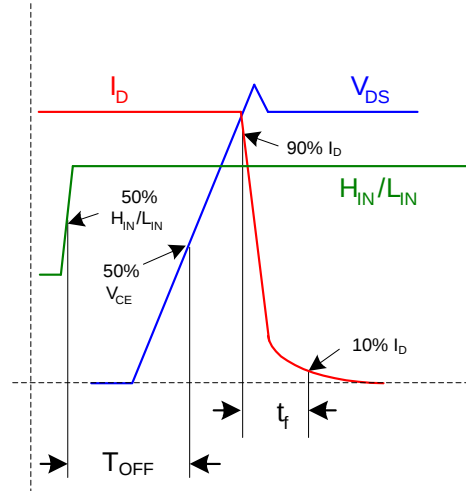


Figure 2b: Input to Output propagation turn-off delay time.

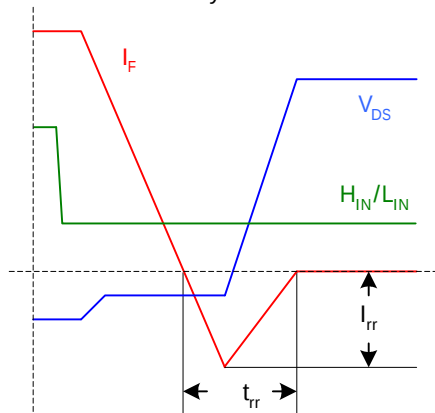


Figure 2c: Diode Reverse Recovery.

Figure 2: Switching Parameter Definitions

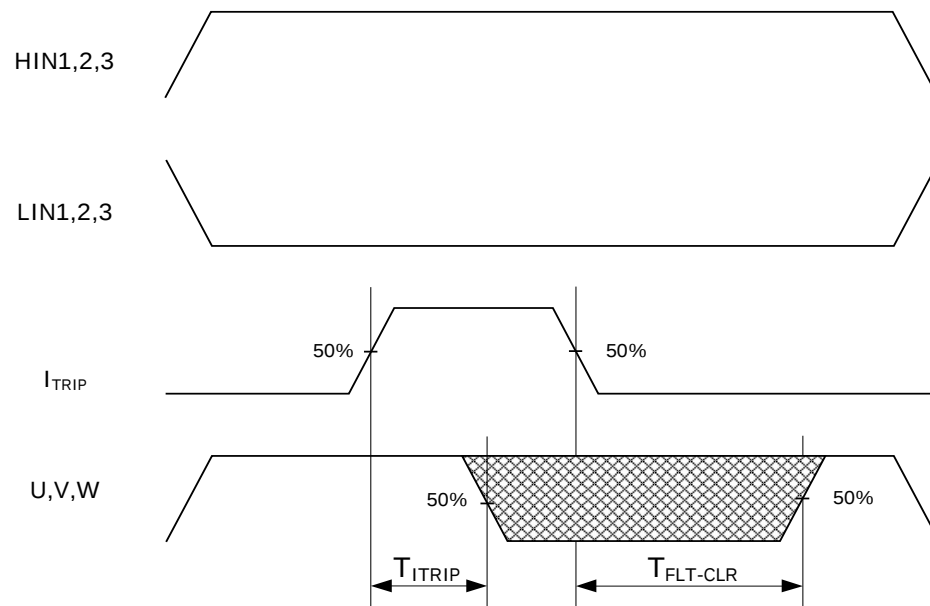
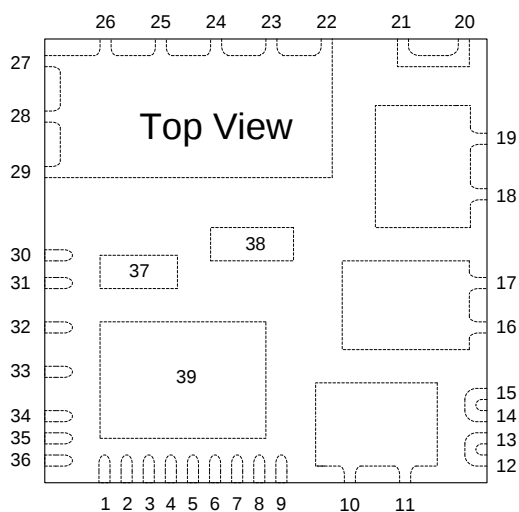


Figure 3: I_{TRIP} Timing Waveform

Module Pin-Out Description

Pin	Name	Description
1	HIN3	Logic Input for High Side Gate Driver - Phase 3
2	LIN1	Logic Input for Low Side Gate Driver - Phase 1
3	LIN2	Logic Input for Low Side Gate Driver - Phase 2
4	LIN3	Logic Input for Low Side Gate Driver - Phase 3
5	/FLT	Fault Output Pin
6	Itrip	Over-Current Protection Pin
7	EN	Enable Pin
8	RCin	Reset Programming Pin
9, 39	VSS, COM	Ground for Gate Drive IC and Low Side Gate Drive Return
10, 11, 30, 37	U, VS1	Output 1, High Side Floating Supply Offset Voltage
12, 13	VR1	Phase 1 Low Side FET Source
14, 15	VR2	Phase 2 Low Side FET Source
16, 17, 38	V, VS2	Output 2, High Side Floating Supply Offset Voltage
18, 19	W, VS3	Output 3, High Side Floating Supply Offset Voltage
20, 21	VR3	Phase 3 Low Side FET Source
22-29	V+	DC Bus Voltage Positive
31	VB1	High Side Floating Supply Voltage 1
32	VB2	High Side Floating Supply Voltage 2
33	VB3	High Side Floating Supply Voltage 3
34	VCC	15V Supply
35	HIN1	Logic Input for High Side Gate Driver - Phase 1
36	HIN2	Logic Input for High Side Gate Driver - Phase 2b



Note

Pins 37 and 38 are not required to be connected electrically on the PCB

All pins with the same name are internally connected. For example, pins 10, 11, 30 and 37 are internally connected.

Current Capability in a Typical Application

Figure 6 shows the current capability for this module at specified conditions. The current capability of the module is affected by application conditions including the PCB layout, ambient temperature, maximum PCB temperature, modulation scheme, PCB copper thickness and so on. The curves below were obtained from measurements carried out on the IRMCS1471_R4 reference design board which includes the IRSM836-025MA and IR's IRMCK171 digital control IC.

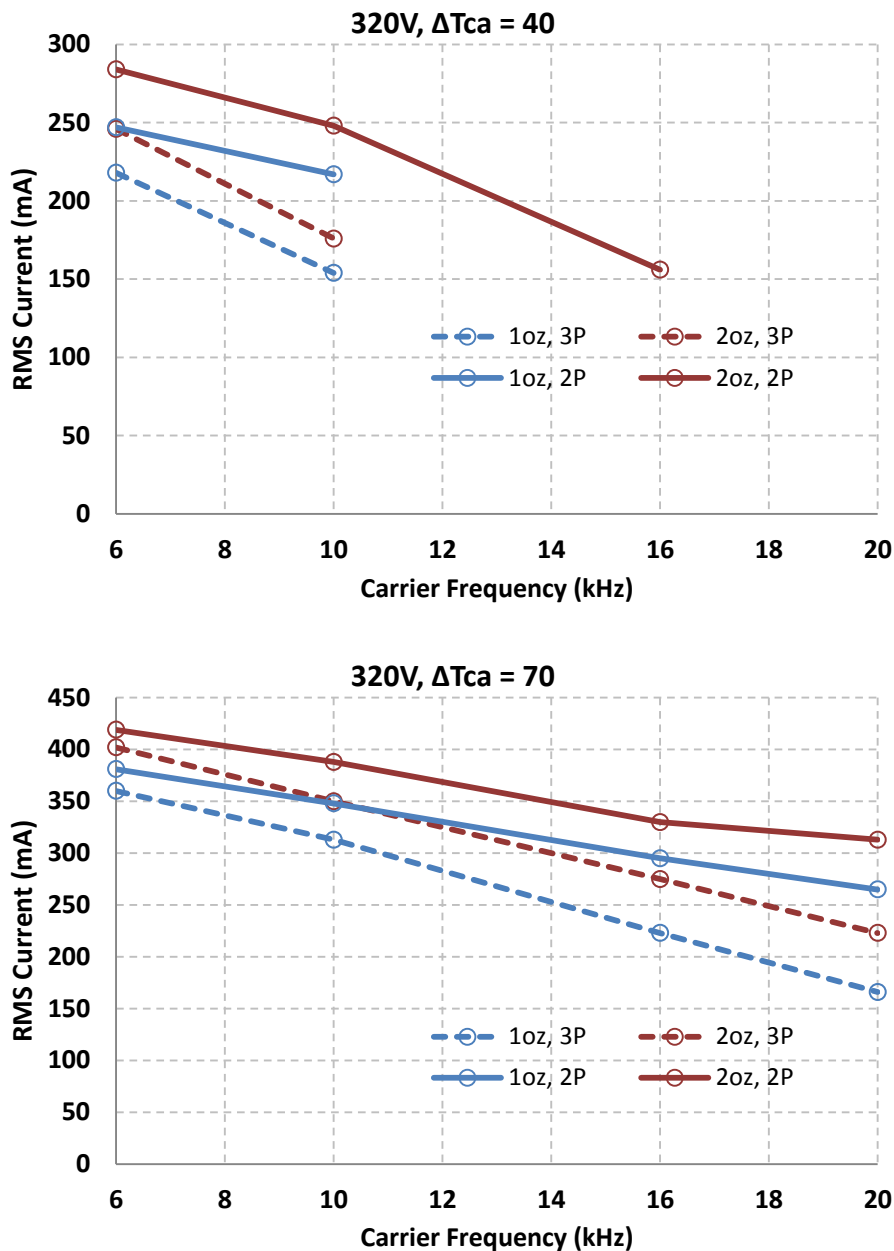


Figure 6: Maximum Sinusoidal Phase Current vs. PWM Switching Frequency
Sinusoidal Modulation, $V^* = 320V$, $PF = 0.98$

PCB Example

Figure 7 below shows an example layout for the application PCB. The effective area of the V+ top-layer copper plane is $\sim 3\text{cm}^2$ in this example. For an FR4 PCB with 1oz copper, $R_{\text{th}(J-A)}$ is about 40°C/W . A lower $R_{\text{th}(J-A)}$ can be achieved using thicker copper and/or additional layers.

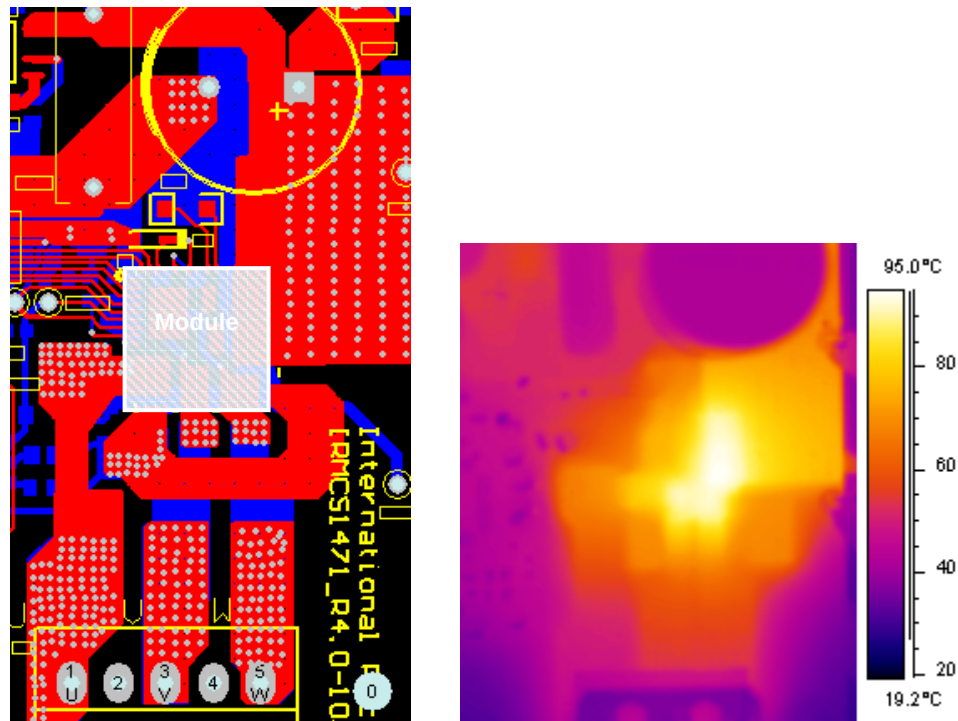
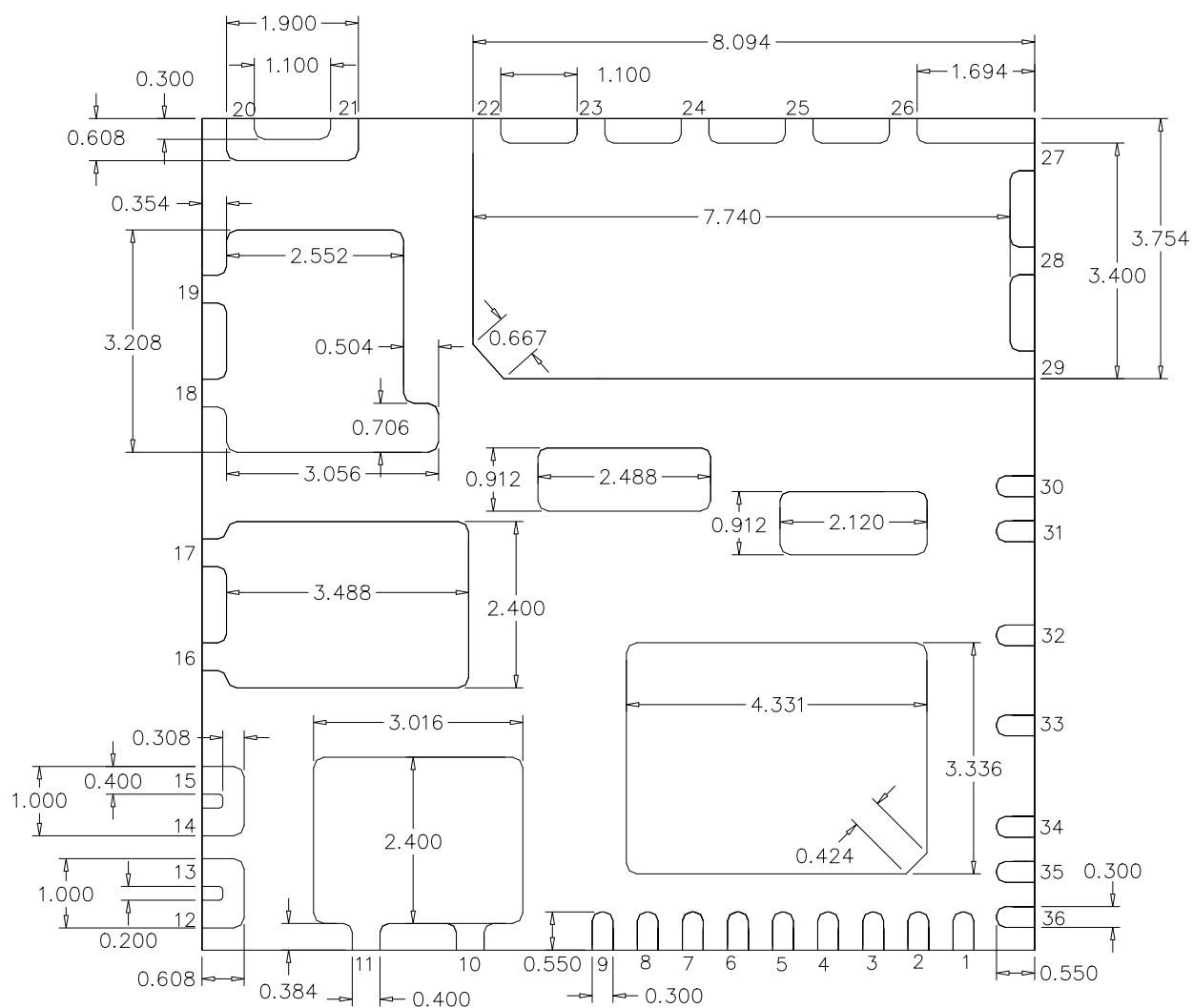
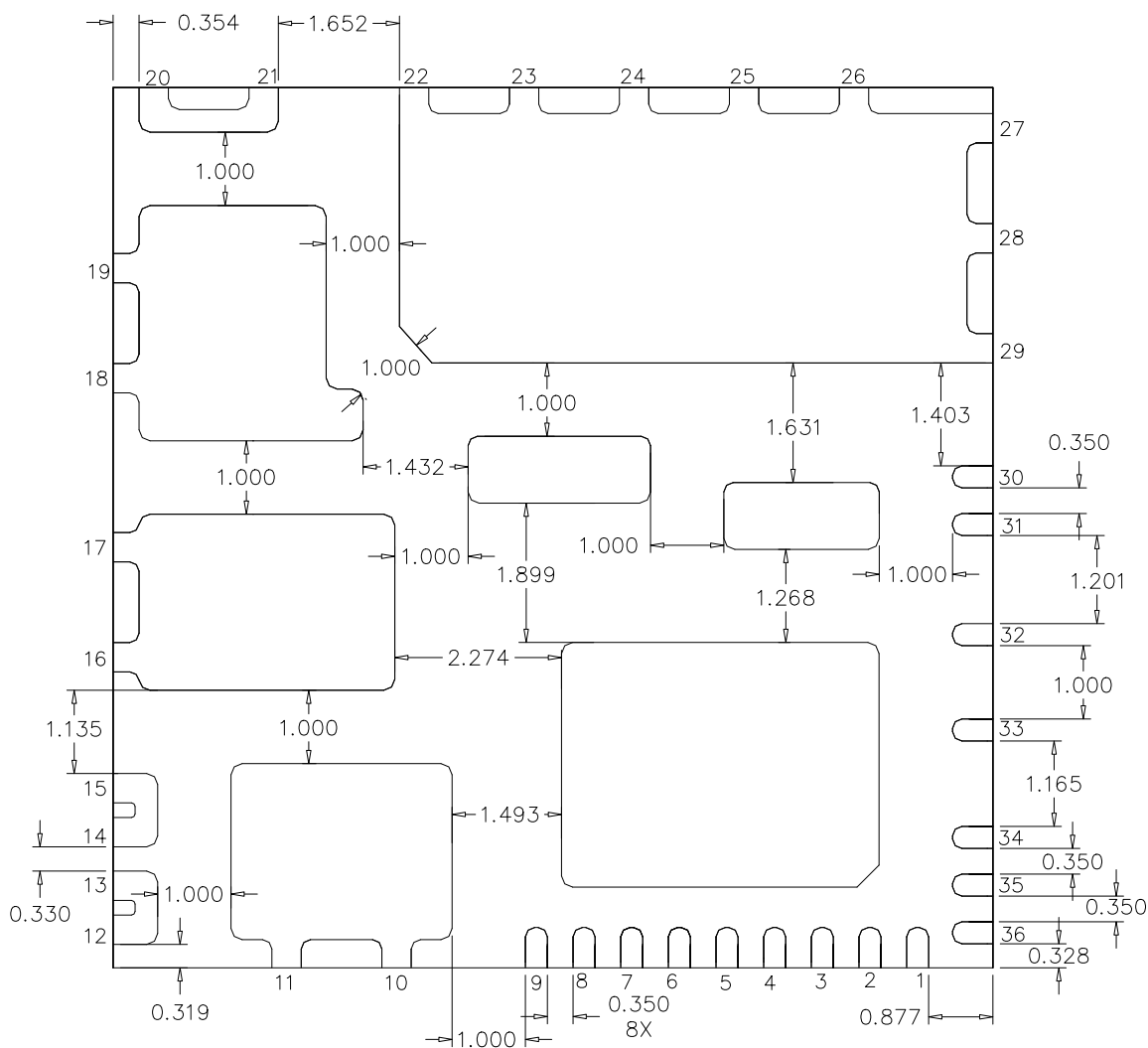


Figure 7: PCB layout example and corresponding thermal image (6kHz, 2P, 2oz, $\Delta T_{\text{ca}}=70^\circ\text{C}$, $V_+ = 320\text{V}$, $I_u = 419\text{mA}_{\text{rms}}$, $P_o = 92\text{W}$)

At the module's typical operating conditions, dV/dt of the phase node voltage is influenced by the load capacitance which includes parasitic capacitance of the PCB, MOSFET output capacitance and motor winding capacitance. To turn off the MOSFET, the load capacitance needs to be charged by the phase current. For the IRMCS1171 reference design, turn-off dV/dt ranges from 2 to 5 V/ns depending on the phase current magnitude. Turn-on dV/dt is influenced by PCB parasitic capacitance and motor winding capacitance and typically ranges from 4 to 6 V/ns. The MOSFET turn-on loss combined with the complimentary body diode reverse recovery loss comprises the majority of the total switching losses. Two-phase modulation can be used to reduce switching losses and run the module at higher phase currents.

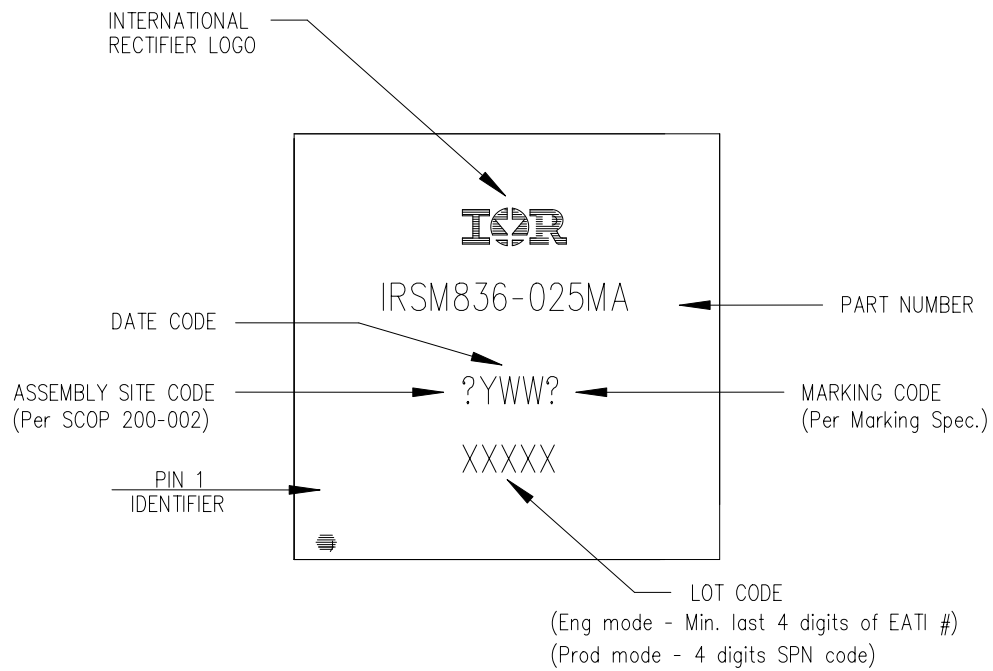
36L Package Outline IRSM836-025MA (Bottom View)


Dimensions in mm

36L Package Outline IRSM836-025MA (Bottom View)


Dimensions in mm

Top Marking



Revision History

January 30, 2013	Formatting corrections; added notes about what pins are internally connected; updated ordering table stating all parts are PbF.
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International
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